

300mm Fully-Automatic LC Tape Laminator

RAD-3600F/12



Outline

–Fully-automatic LC Tape laminator which laminates Adwill LC Tape to wafer backside after back grinding.

–Performs the following functions:

- Wafer alignment
- LC Tape pre-cutting
- LC Tape lamination
- Release liner peeling

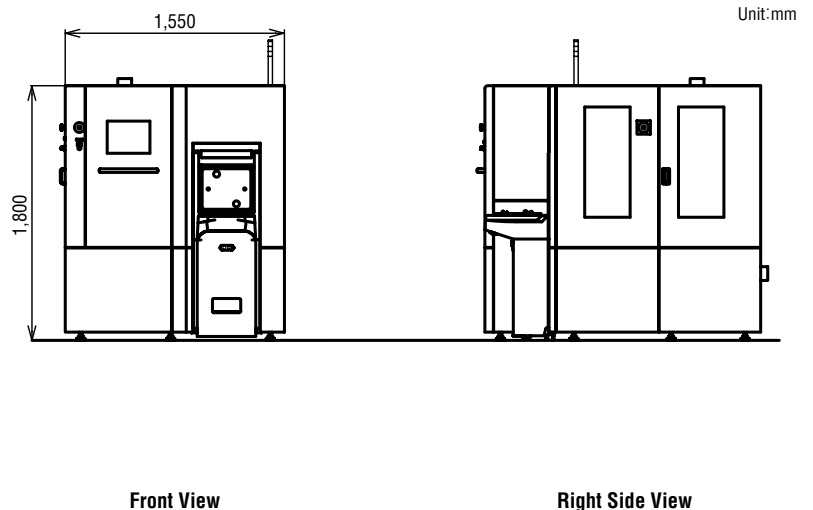
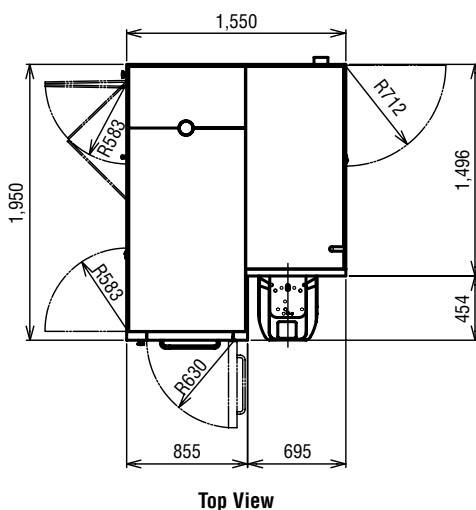
Options ·Host Communication Function (Communication Format :
Conforms to SECS-I and HSMS/Software : Conforms to GEM)

·Double Cassette Loading

·Wafer ID Reader

Suitable Tape ·Backside coating tape : Adwill LC Tape

External View



Facility

Power Supply	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
	Power consumption	: 6.0kW
Air Supply	Air pressure	: 0.5-0.8MPa
	Air consumption	: >150L/min (ANR)
Vacuum Supply	Vacuum pressure	: >-80kPa

Applicable Wafer Size 200mm, 300mm

Size Width : 1,550mm
Depth : 1,950mm
Height : 1,800mm
(excluding the signal tower and protruding parts)

Weight 1,500kg

UPH 30 wafers/hour (excludes setting time)

The above processing capacity is based on following conditions:

Wafer : 300mm diameter non-polished mirror wafer
LC Tape : LC2850(40) from LINTEC